

#### **General Description**

The WSD3810DN is the highest performance trench Dual N-Ch MOSFET with extreme high cell density, which provide excellent  $R_{DSON}$  and gate charge for most of the synchronous buck converter applications .

The WSD3810DN meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

#### **Features**

Advanced high cell density Trench technology

Super Low Gate Charge

Excellent CdV/dt effect decline

100% EAS Guaranteed

Green Device Available

#### **Product Summery**

Bvdss	Rdson	Iσ	Ітем
30V	10.8mΩ	18A	Q1
30V	10.5mΩ	18A	Q2

#### **Applications**

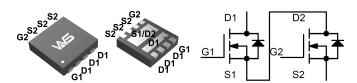
High Frequency Point-of-Load Synchronous

Buck Converter for MB/NB/UMPC/VGA

Networking DC-DC Power System

Load Switch

#### **DFN3X3** Asymmetric Dual Pin Configuration



# Absolute Maximum Ratings @TA=25°C unless otherwise noted

Symbol	Parameter		Q1	Q2	Units	
V <sub>DS</sub>	Drain-Source Voltage		30	30	V	
V <sub>GS</sub>	Gate-Source Voltage		±20	±20	V	
Ιb	Drain Current (Continuous) *AC	Tc=25°C	18	18	Α.	
		Tc=100°C	12.3	12.3	A	
Ірм	Drain Current (Pulse) *B		45	45	A	
PD	Power Dissipation	Tc=25°C	20	20	W	
EAS	Single Pulse Avalanche Energy	VDD=25V,VGS=10V,L=1mH,R G=25Ω	11	11	mJ	
Rejc	Thermal Resistance Junction to Case		6	6	°C/W	
TJ//Tstg	Operating Temperature/ Storage Temperature		-55~150	-55~150	$^{\circ}$	



#### Q1 Electrical Characteristics @TA=25°C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Static						
$V_{({\rm BR}){\rm DSS}}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V$ , $I_D = 250 \mu A$	30			V
Idss	Zero Gate Voltage Drain Current	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ
Igss	Gate Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	nA
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{DS} = 250 \mu A$	1	1.6	2.5	V
_	Drain-Source On-state Resistance	$V_{GS} = 10V, I_D = 10A$		9	10.8	mΩ
RDS(on)		$V_{GS} = 4.5V, I_D = 8A$		12	17.5	mΩ
gFS	Forward Transconductance	$V_{DS} = 5V$ , $I_D = 5A$		12		S
$V_{\mathrm{SD}}$	Diode Forward Voltage	$I_{SD} = 1A$ , $V_{GS} = 0V$			1.3	V
Switching				I		
Qg	Total Gate Charge			8		nC
Qgs	Gate-Source Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =5A		1.6		nC
Qgd	Gate-Drain Charge			1.2		nC
td (on)	Turn-on Delay Time	$V_{GS}$ =10V, $V_{DD}$ =15V, $I_{D}$ =1A, $R_{G}$ =6 $\Omega$		8.5		ns
tr	Turn-on Rise Time			10		ns
td(off)	Turn-off Delay Time			14		ns
tf	Turn-off Fall Time			10.6		ns
Dynamic					<u>.                                    </u>	
Ciss	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		455		pF
Coss	Output Capacitance			318		pF
Crss	Reverse Transfer Capacitance			22		pF

A: The value of R $\theta$ JA is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with TA=25°C. The value in any given application depends on the user's specific board design. B: Repetitive rating, pulse width limited by junction temperature. C: The current rating is based on the t $\leq$  10s junction to ambient thermal resistance rating.



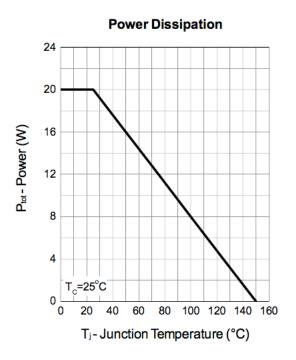
#### Q2 Electrical Characteristics @TA=25°C unless otherwise noted

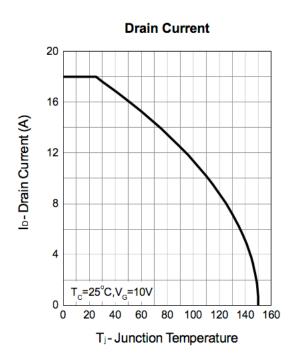
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Igss	Gate Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	nA
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D	Drain-Source On-state Resistance	$V_{GS} = 10V, I_D = 10A$		8.5	10.5	mΩ
RDS(on)		$V_{GS} = 4.5V, I_D = 8A$		12.5	16	mΩ
gFS	Forward Transconductance	$V_{DS} = 5V$ , $I_D = 5A$		12		S
$V_{\mathrm{SD}}$	Diode Forward Voltage	$I_{SD} = 1A$ , $V_{GS}=0V$			1.3	V
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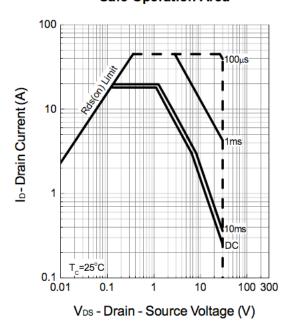


#### • Q1 TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

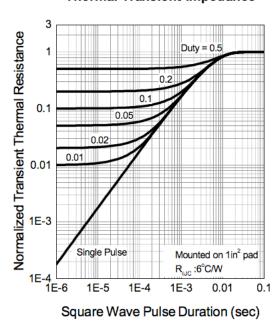




## Safe Operation Area

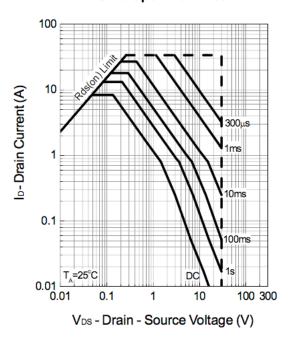


#### **Thermal Transient Impedance**

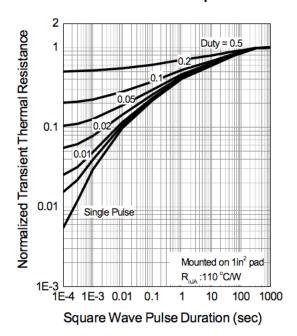




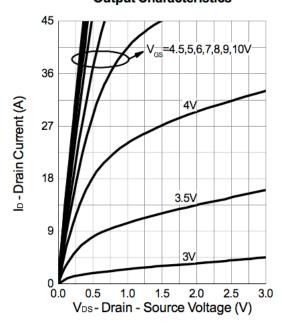
## Safe Operation Area



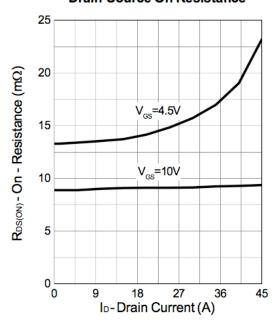
#### **Thermal Transient Impedance**



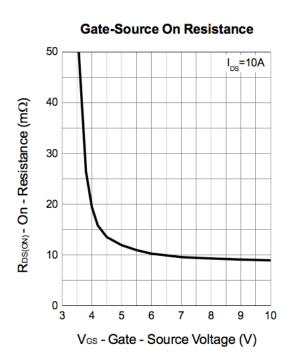
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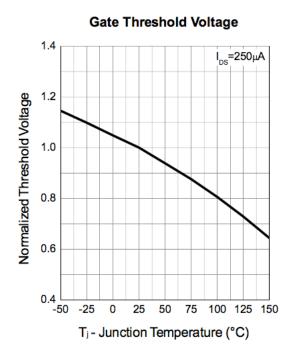


#### **Drain-Source On Resistance**

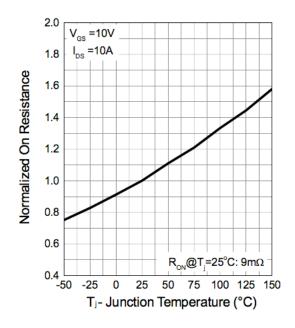




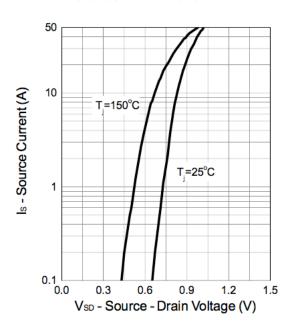




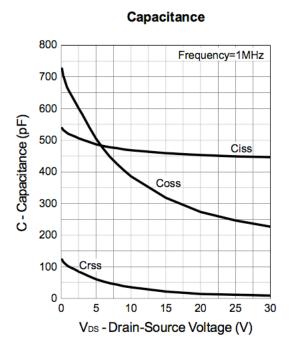
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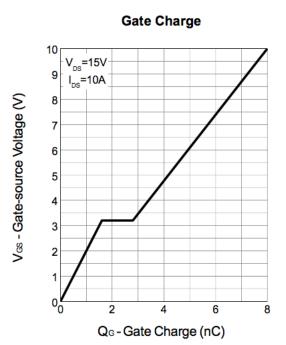


#### Source-Drain Diode Forward



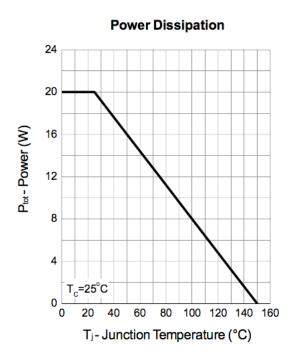


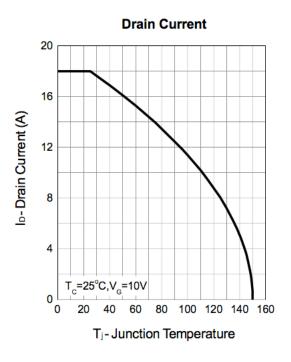




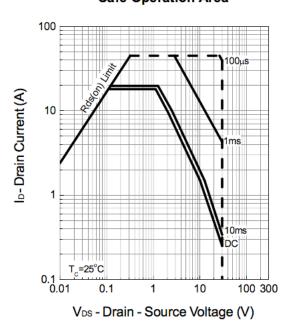


#### • Q2 TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

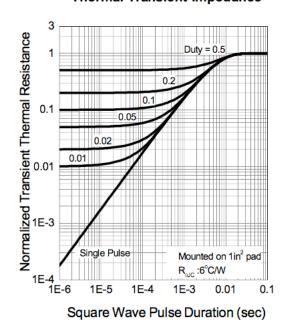




# Safe Operation Area

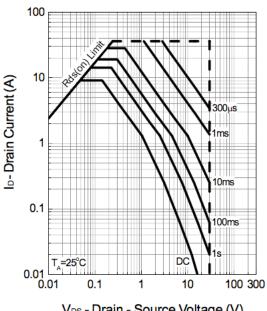


#### Thermal Transient Impedance

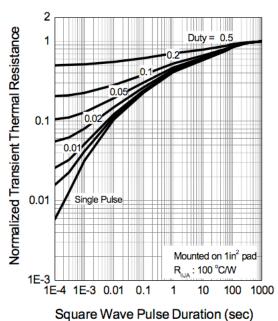




#### Safe Operation Area

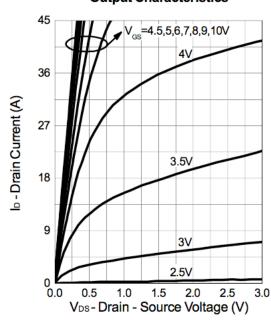


#### **Thermal Transient Impedance**

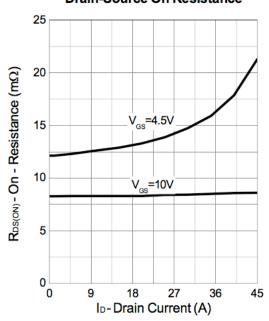


V<sub>DS</sub> - Drain - Source Voltage (V) Square Way

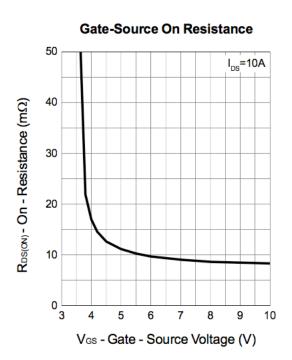
# **Output Characteristics**

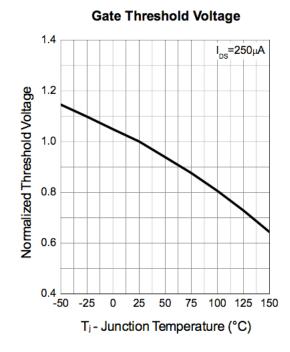


#### **Drain-Source On Resistance**

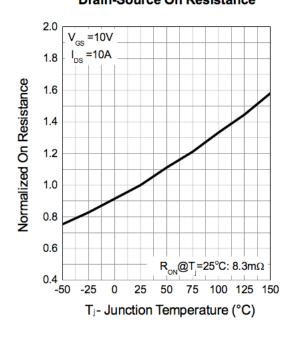




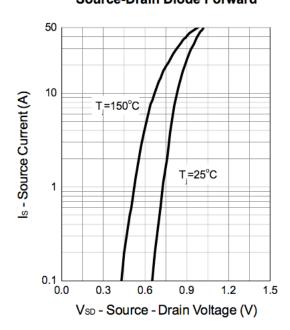




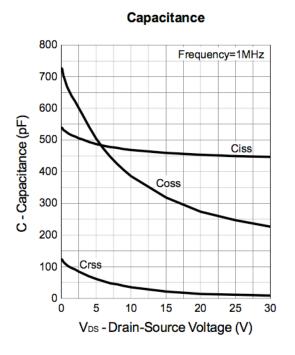
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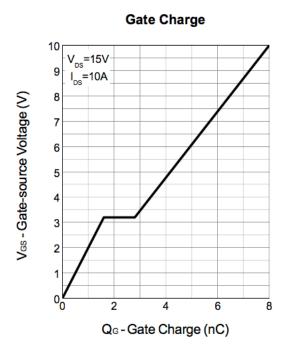


# Source-Drain Diode Forward











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